



## Description

The HSU3008 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

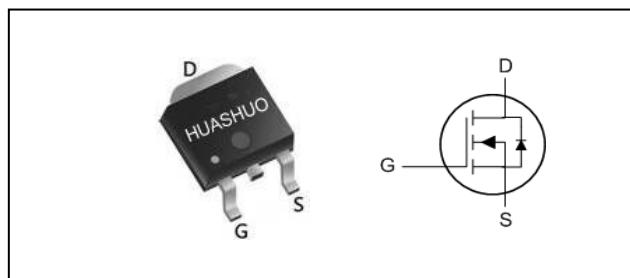
The HSU3008 meet the RoHS and Green Product requirement with full function reliability approved.

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

## Product Summary

V <sub>DS</sub>	30	V
R <sub>DS(ON),max</sub>	25	mΩ
I <sub>D</sub>	24	A

## TO252 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sub>1</sub>	24	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sub>1</sub>	15	A
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sub>1</sub>	7.3	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sub>1</sub>	5.8	A
I <sub>DM</sub>	Pulsed Drain Current <sub>2</sub>	50	A
EAS	Single Pulse Avalanche Energy <sub>3</sub>	8.1	mJ
I <sub>AS</sub>	Avalanche Current	12.7	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sub>4</sub>	20.8	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sub>4</sub>	2	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sub>1</sub>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sub>1</sub>	---	6	°C/W



**N-Ch 30V Fast Switching MOSFETs**

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_{\text{D}}=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $\text{I}_{\text{D}}=1\text{mA}$	---	0.023	---	$\text{V}/^{\circ}\text{C}$
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_{\text{D}}=10\text{A}$	---	---	25	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_{\text{D}}=8\text{A}$	---	---	38	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_{\text{D}}=250\mu\text{A}$	1.0	---	2.5	V
$\Delta \text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS(th)}}$ Temperature Coefficient		---	-4.2	---	$\text{mV}/^{\circ}\text{C}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=25^{\circ}\text{C}$	---	---	1	$\text{uA}$
		$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=55^{\circ}\text{C}$	---	---	5	
$\text{I}_{\text{CSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}$ , $\text{I}_{\text{D}}=10\text{A}$	---	5.5	---	S
$\text{R}_{\text{g}}$	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.3	---	$\Omega$
$\text{Q}_{\text{g}}$	Total Gate Charge (4.5V)	$\text{V}_{\text{DS}}=15\text{V}$ , $\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_{\text{D}}=10\text{A}$	---	4.9	---	$\text{nC}$
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	1.66	---	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	1.85	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=15\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{R}_{\text{g}}=3.3\Omega$ $\text{I}_{\text{D}}=10\text{A}$	---	1.6	---	$\text{ns}$
$\text{T}_r$	Rise Time		---	15.8	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	13	---	
$\text{T}_f$	Fall Time		---	4.8	---	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=15\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	416	---	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		---	62	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	51	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_{\text{s}}$	Continuous Source Current <sup>1,5</sup>	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$ , Force Current	---	---	24	A
$\text{I}_{\text{SM}}$			---	---	50	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_{\text{s}}=1\text{A}$ , $T_J=25^{\circ}\text{C}$	---	---	1.2	V
$\text{t}_{\text{rr}}$	Reverse Recovery Time	$\text{I}_{\text{F}}=10\text{A}$ , $d\text{I}/dt=100\text{A}/\mu\text{s}$ , $T_J=25^{\circ}\text{C}$	---	8.7	---	$\text{nS}$
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge		---	1.95	---	$\text{nC}$

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=25\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{L}=0.1\text{mH}$ , $\text{I}_{\text{AS}}=12.7\text{A}$
- 4.The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 5.The data is theoretically the same as  $\text{I}_{\text{D}}$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



## N-Ch 30V Fast Switching MOSFETs

### Typical Characteristics

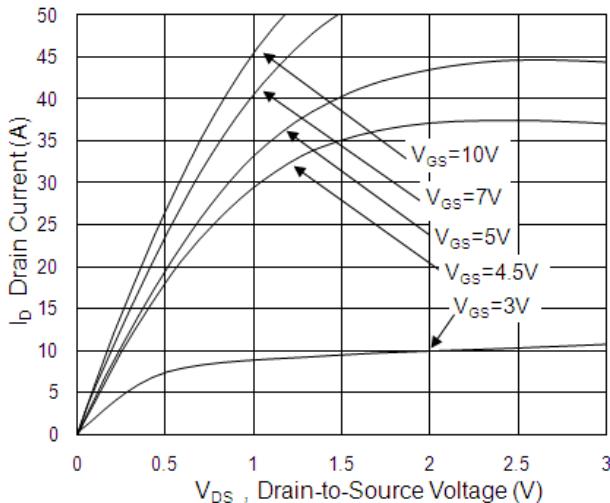


Fig.1 Typical Output Characteristics

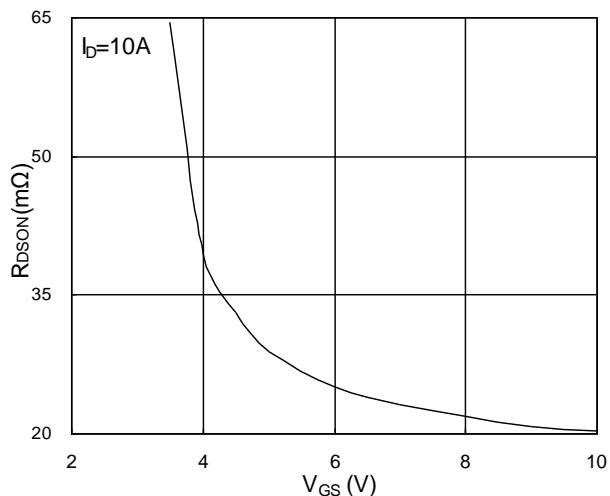


Fig.2 On-Resistance vs. Gate-Source

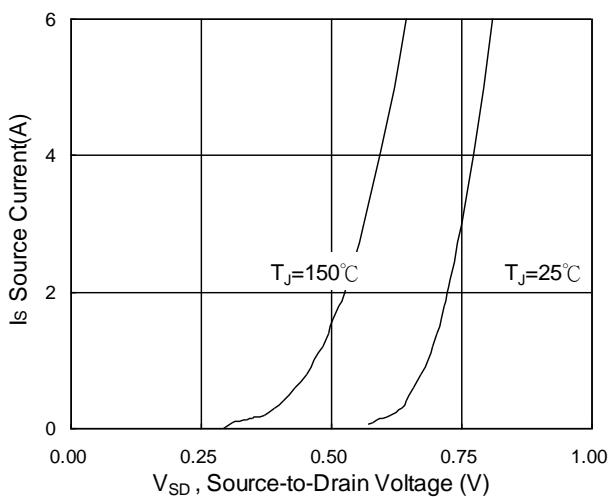


Fig.3 Forward Characteristics Of Reverse

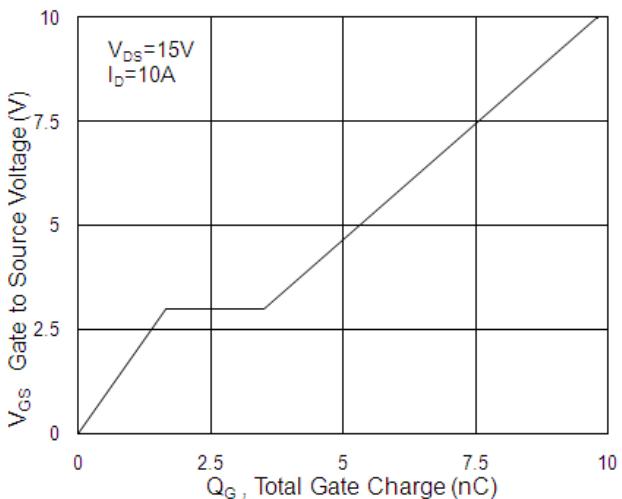


Fig.4 Gate-Charge Characteristics

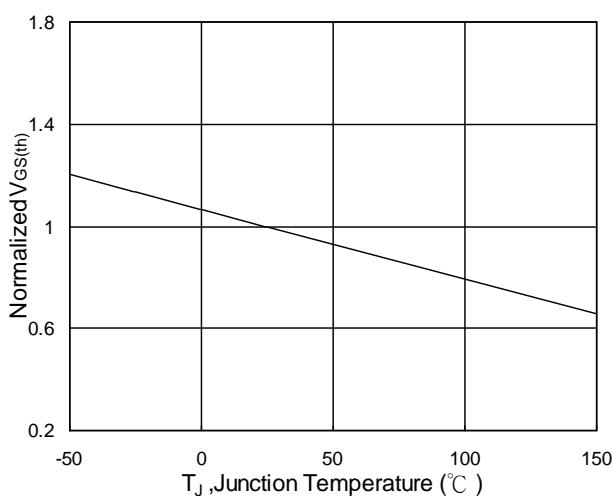


Fig.5 Normalized  $V_{GS(\text{th})}$  vs.  $T_J$

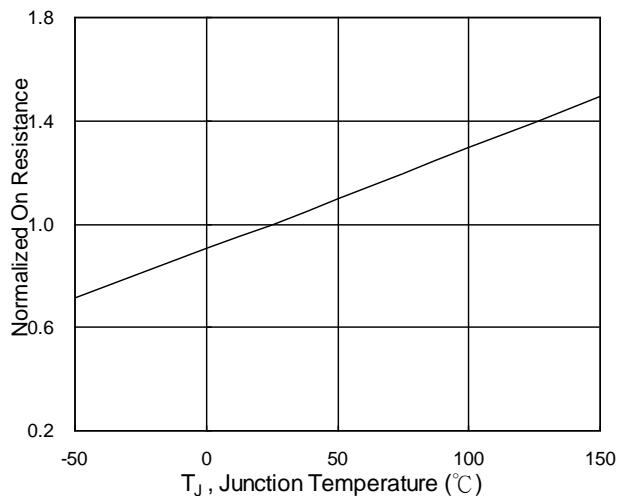


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



HUASHUO  
SEMICONDUCTOR

HSU3008

### N-Ch 30V Fast Switching MOSFETs

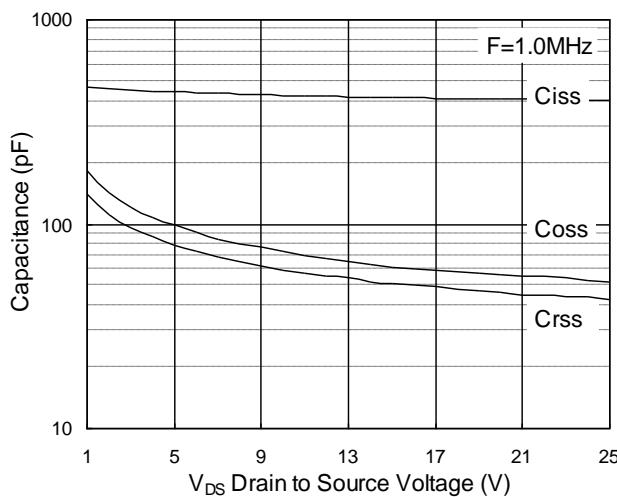


Fig.7 Capacitance

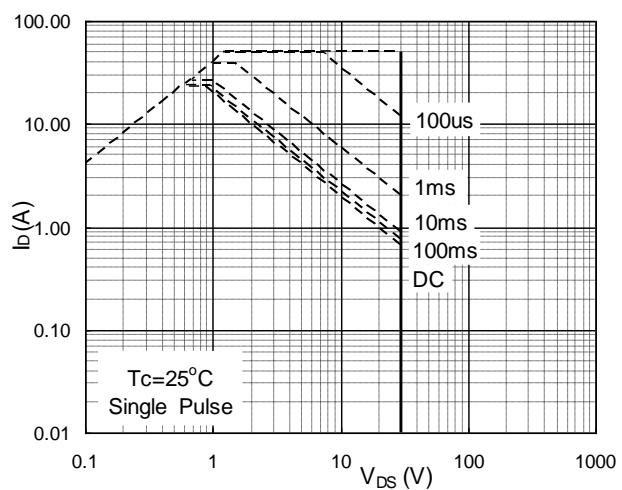


Fig.8 Safe Operating Area

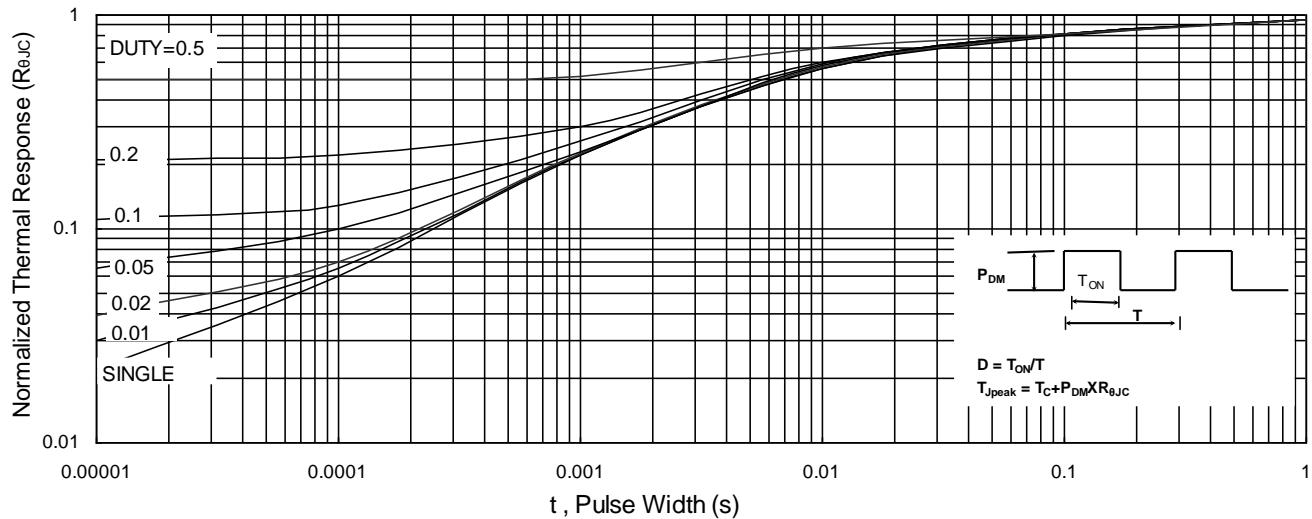


Fig.9 Normalized Maximum Transient Thermal Impedance

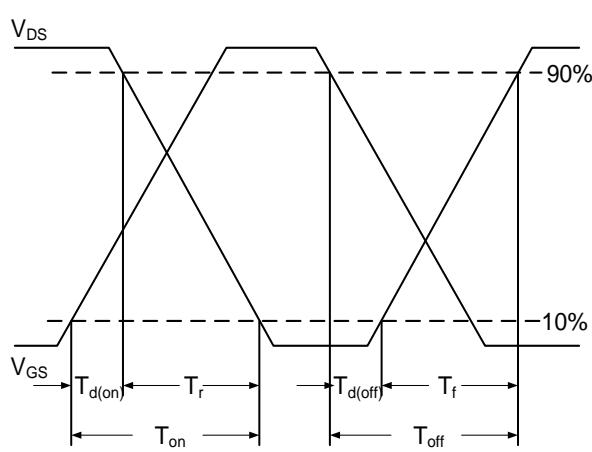


Fig.10 Switching Time Waveform

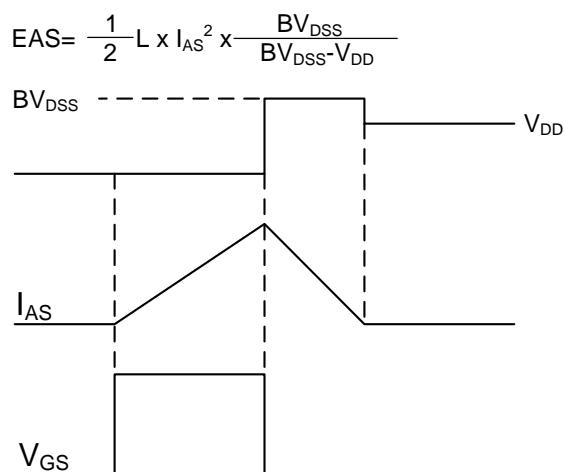
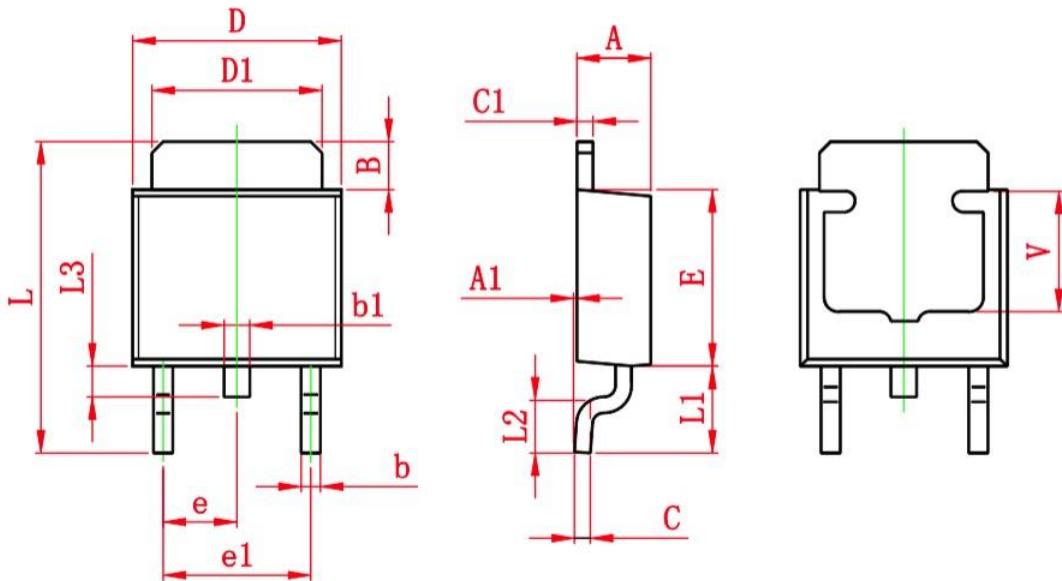


Fig.11 Unclamped Inductive Switching



## Ordering Information

Part Number	Package code	Packaging
HSU3008	TO252-2	2500/Tape&Reel



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800 REF.		0.150 REF.	